



DESCRIPTION

The ABS201~ABS210 are available in ABS package.

FEATURES

- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000V
- Forward Current - 2A
- High Surge Current Capability
- Designed for Surface Mount Application
- Available in ABS package

ORDERING INFORMATION

Package Type	Part Number
ABS	ABS201
	ABS202
	ABS204
	ABS206
	ABS208
	ABS210
Note	SPQ: 5,000pcs/Reel
AiT provides all RoHS Compliant Products	

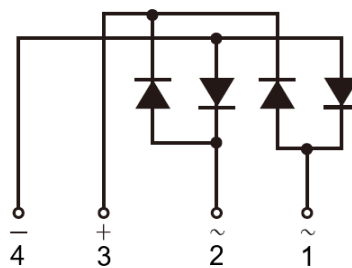
MECHANICAL DATA

Case: ABS

Terminals: Solderable per MIL-STD-750,
Method 2026

Approx. Weight: 88mg 0.0031oz

PIN DESCRIPTION



1. Input Pin (~)
2. Input Pin (~)
3. Output Anode (+)
4. Output Cathode (-)



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbol	ABS201	ABS202	ABS204	ABS206	ABS208	ABS210	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_L=100^\circ\text{C}$	I_o	2.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	50						A
Forward Voltage Per Element	$I_F=2.0\text{A}$ V_F	1.0						V
Maximum DC Reverse Current at Rated DC Blocking Voltage	$T_A=25^\circ\text{C}$ $T_A=125^\circ\text{C}$ I_R	5.0 100						μA
Typical Junction Capacitance ^{NOTE1}	C_j	25						pF
Typical Thermal Resistance ^{NOTE2}	$R_{\theta JA}$	65						$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 ~ 150						$^\circ\text{C}$

NOTE1: Measured at 1MHz and applied reverse voltage of 4V D.C.

NOTE2: Mounted on glass epoxy PC board with 4x(5x5mm²) copper pad.



TYPICAL CHARACTERISTICS

Figure 1. Average Rectified Output Current

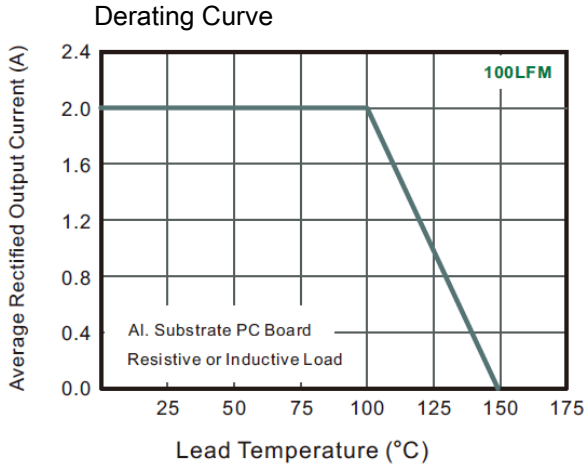


Figure 2. Typical Reverse Characteristics

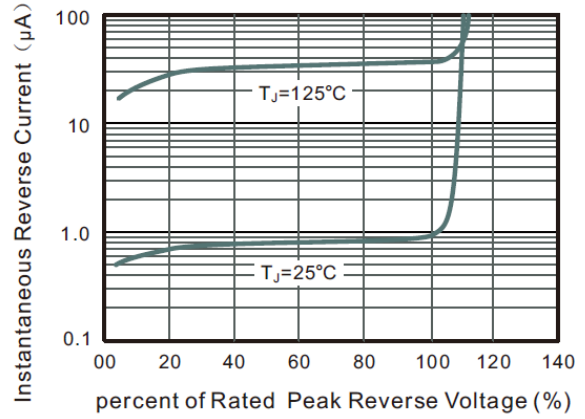


Figure 3. Typical Instantaneous Forward Characteristics

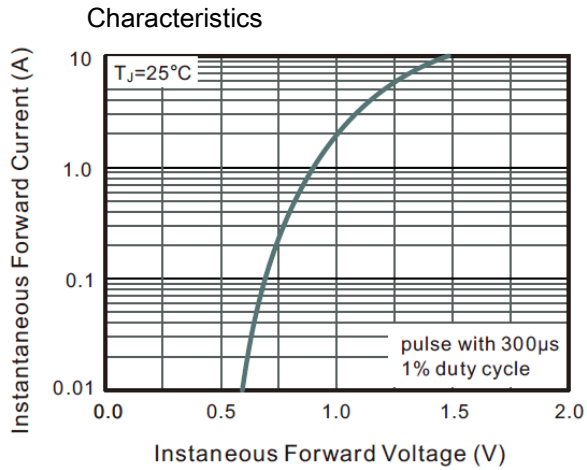


Figure 4. Typical Junction Capacitance

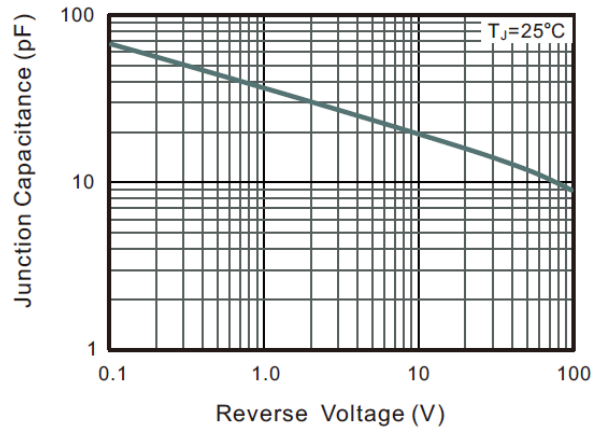
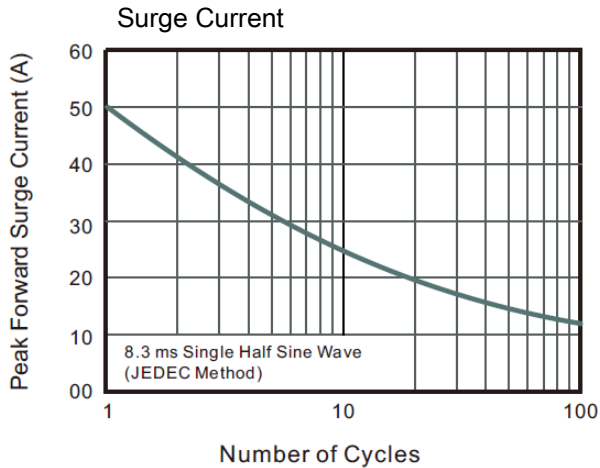


Figure 5. Maximum Non-Repetitive Peak Forward Surge Current

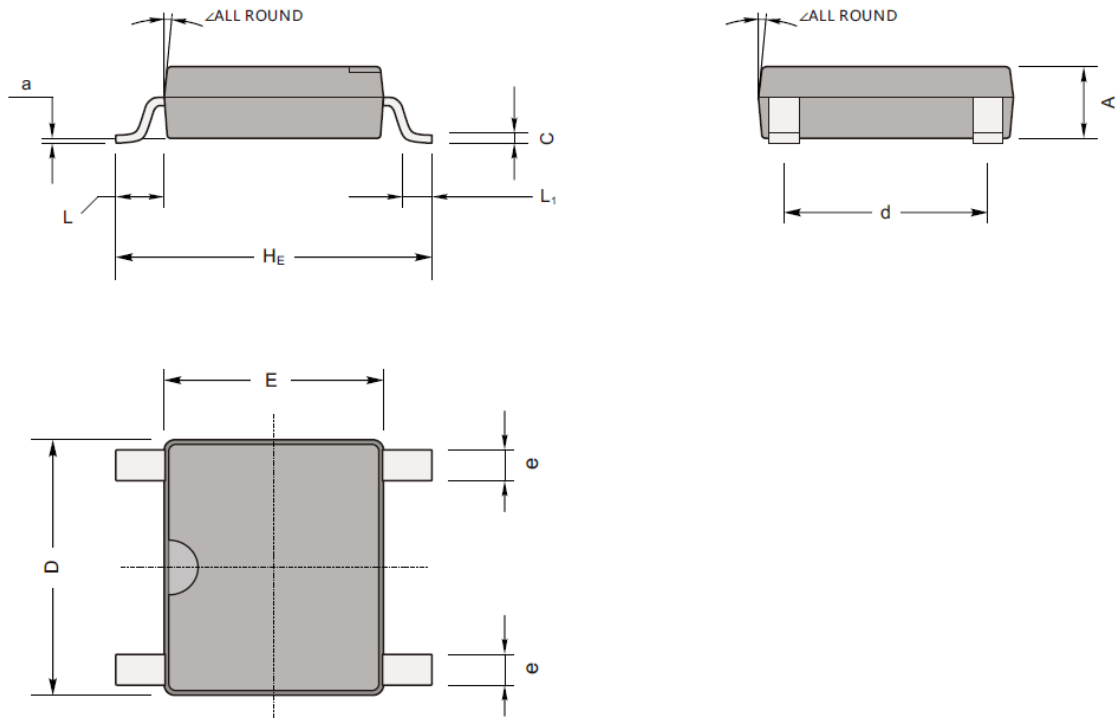




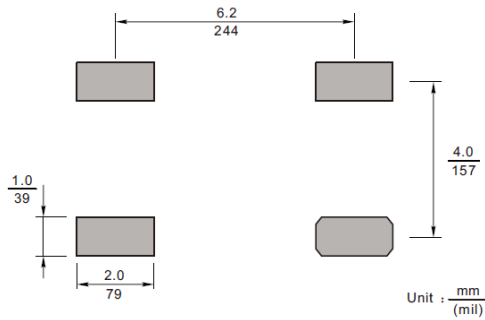
PACKAGE INFORMATION

Dimension in ABS Package (Unit: mm/mil)

Plastic surface mounted package; 4 leads



The recommended mounting pad size



UNIT		A	C	D	E	HE	d	e	L	L1	a	∠
mm	Min	1.3	0.15	4.9	4.2	6.0	3.8	0.5	0.95	0.6	0.2	7°
	Max	1.5	0.22	5.2	4.5	6.4	4.2	0.7				
mil	Min	51	5.9	193	166	236	150	20	37	24	4	
	Max	59	8.7	205	177	252	165	28				



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